CLAIMS

1. A sealing material for semiconductor manufacturing devices, comprising a crosslinked product of a fluorine rubber composition,

the fluorine rubber composition including a hydrogen atom-containing fluorine rubber, a hydrogen atom-containing fluororesin (which does not include a fluorinecontaining thermoplastic elastomer), an organic peroxide, and a co-crosslinking agent,

the hydrogen atom-containing fluorine rubber including a vinylidene fluoridehexafluoropropylene-tetrafluoroethylene copolymer,

the hydrogen atom-containing fluororesin being at least one compound selected from the group consisting of polyvinylidene fluoride, a vinylidene fluoridehexafluoropropylene copolymer, and a tetrafluoroethylene-ethylene copolymer,

a content of the hydrogen atom-containing fluororesin being 10 to 20 parts by weight relative to 100 parts by weight of the hydrogen atom-containing fluorine rubber.

2. The sealing material according to claim 1, wherein the sealing material contains no inorganic filler.

3. A method for producing the sealing material for semiconductor manufacturing devices according to claim 1 or 2, the method comprising a step of crosslinking and molding the fluorine rubber composition.

4. A method for producing the sealing material for semiconductor manufacturing devices according to claim 1 or 2, the method comprising:

a first crosslinking step of partially crosslinking the fluorine rubber composition to produce a first crosslinked product that is capable of being molded; and

a second crosslinking step of crosslinking the first crosslinked product with an ionizing radiation to produce a second crosslinked product.

5. The production method according to claim 4, wherein the production method further comprises a molding step of molding the first crosslinked product between the first crosslinking step and the second crosslinking step.

6. The production method according to claim 5, wherein the first crosslinked product is molded by extrusion molding or injection molding.

7. The production method according to any one of claims 4 to 6, wherein the fluorine rubber composition is crosslinked with heat in the first crosslinking step.